

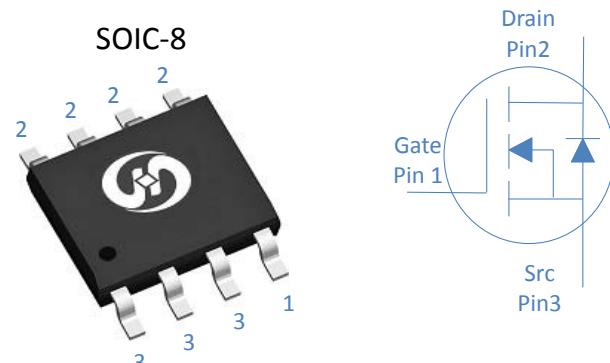
100V N-Ch Power MOSFET
Feature

- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

V_{DS}	100	V
$R_{DS(on),typ}$	$V_{GS}=10V$	7.1 mΩ
$R_{DS(on),typ}$	$V_{GS}=4.5V$	8.4 mΩ
I_D		14 A

Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial



Part Number	Package	Marking
HGS085N10SL	SOIC-8	GS085N10SL

Absolute Maximum Ratings at $T_j=25^\circ C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ C$	14	A
		$T_C=100^\circ C$	8.9	
Drain to Source Voltage	V_{DS}	-	100	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	80	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.1mH, T_C=25^\circ C$	80	mJ
Power Dissipation	P_D	$T_C=25^\circ C$	3.1	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	°C

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Lead	$R_{\theta JL}$	23	°C/W
Thermal Resistance Junction-Ambient ($t \leq 10s$)	$R_{\theta JA}$	40	°C/W
Thermal Resistance Junction-Ambient (steady state)		75	°C/W

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_D=250\mu\text{A}$	100	-	-	V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_D=250\mu\text{A}$	1.4	1.9	2.4	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=100\text{V}, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	±100	nA
Drain to Source on Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}}=10\text{V}, I_D=14\text{A}$	-	7.1	8.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_D=10\text{A}$	-	8.4	10.5	
Transconductance	g_{fs}	$V_{\text{DS}}=5\text{V}, I_D=14\text{A}$	-	70	-	S
Gate Resistance	R_G	$V_{\text{GS}}=0\text{V}, V_{\text{DS}} \text{ Open}, f=1\text{MHz}$	-	1.5	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=50\text{V}, f=1\text{MHz}$	-	3350	-	pF
Output Capacitance	C_{oss}		-	270	-	
Reverse Transfer Capacitance	C_{rss}		-	15	-	
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{DD}}=50\text{V}, I_D=14\text{A}, V_{\text{GS}}=10\text{V}$	-	49	-	nC
Total Gate Charge	$Q_g(4.5\text{V})$		-	21	-	
Gate to Source Charge	Q_{gs}		-	8	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	7	-	
Turn on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=50\text{V}, I_D=14\text{A}, V_{\text{GS}}=10\text{V}, R_G=10\Omega,$	-	10	-	ns
Rise time	t_r		-	5	-	
Turn off Delay Time	$t_{\text{d}(\text{off})}$		-	32	-	
Fall Time	t_f		-	6	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{\text{GS}}=0\text{V}, I_F=14\text{A}$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=50\text{V}, I_F=14\text{A}, dI_F/dt=500\text{A}/\mu\text{s}$	-	47	-	ns
Reverse Recovery Charge	Q_{rr}		-	226	-	nC

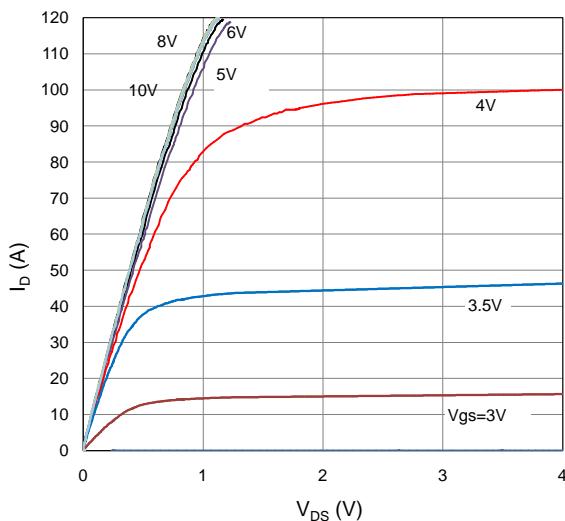
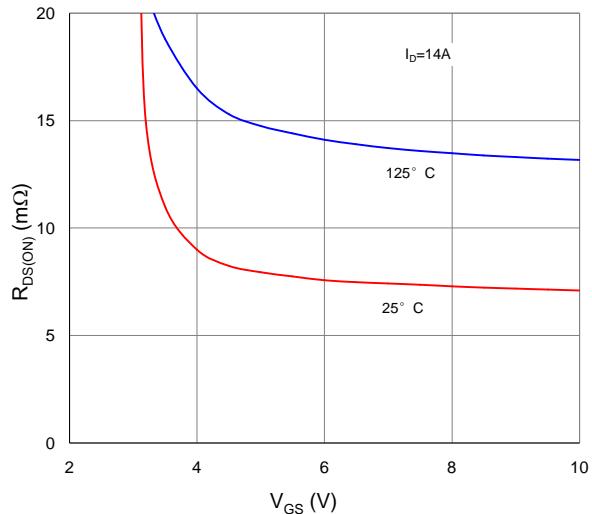
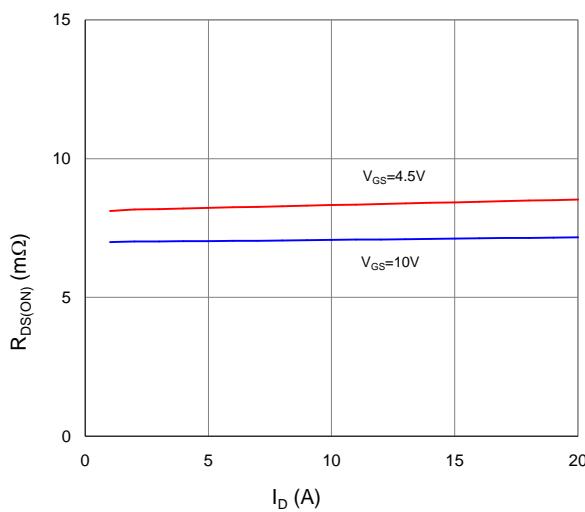
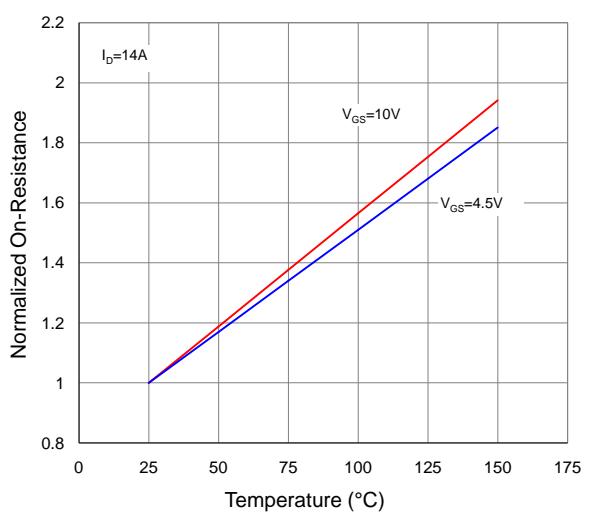
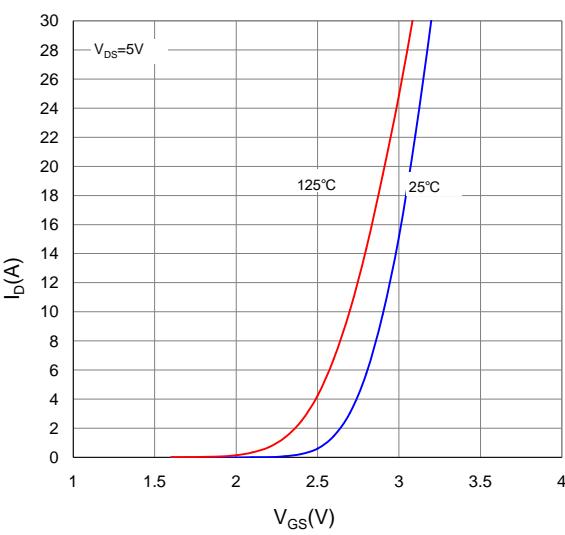
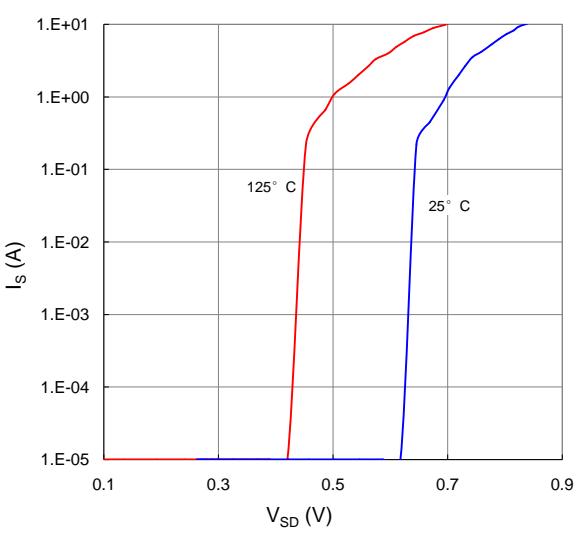
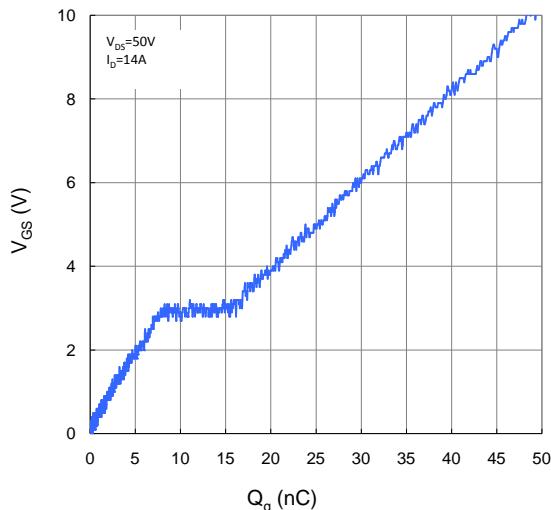
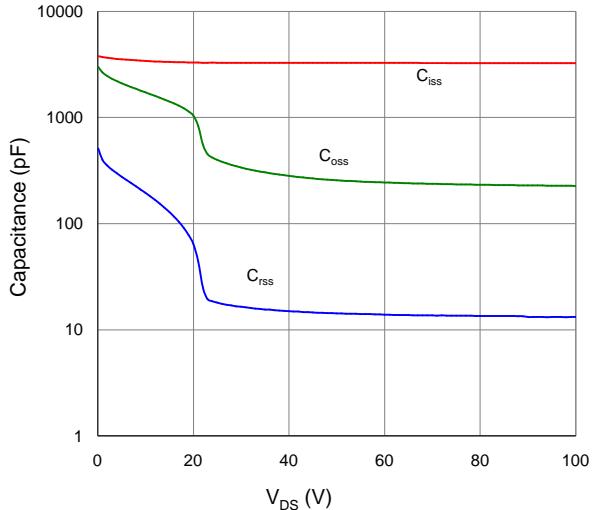
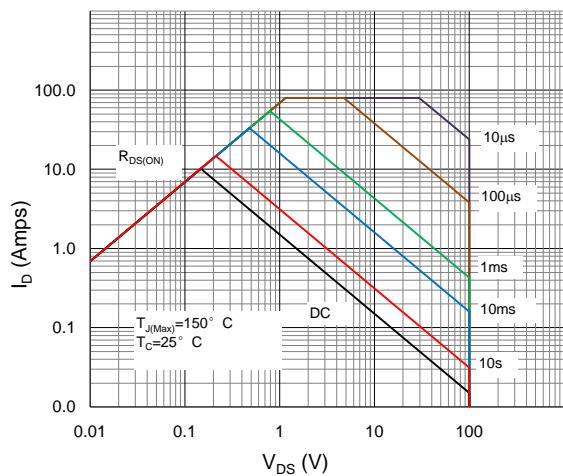
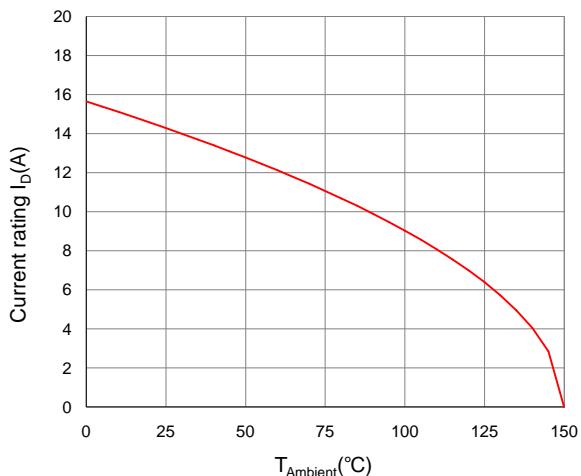
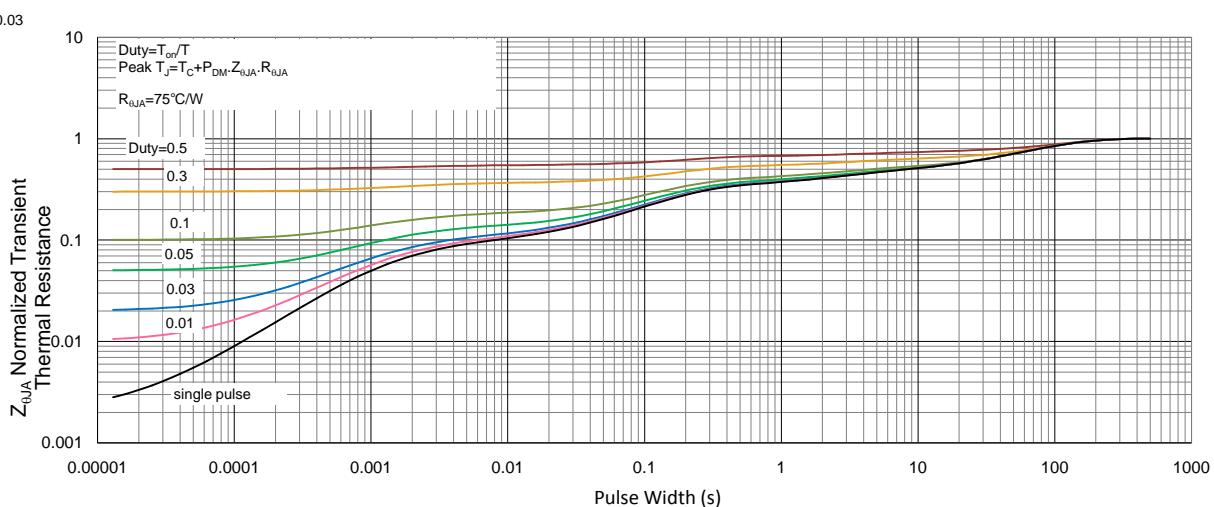
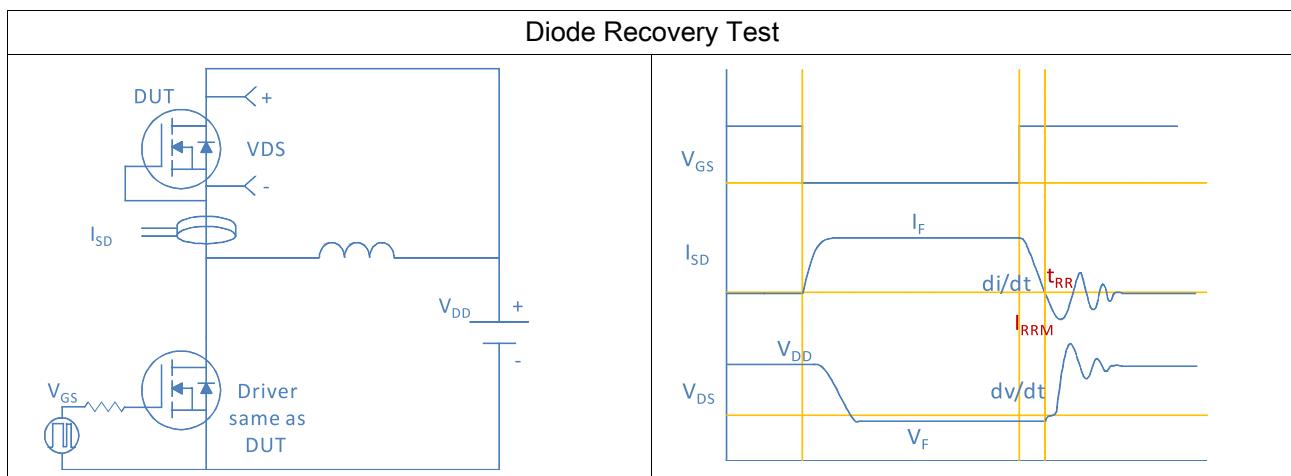
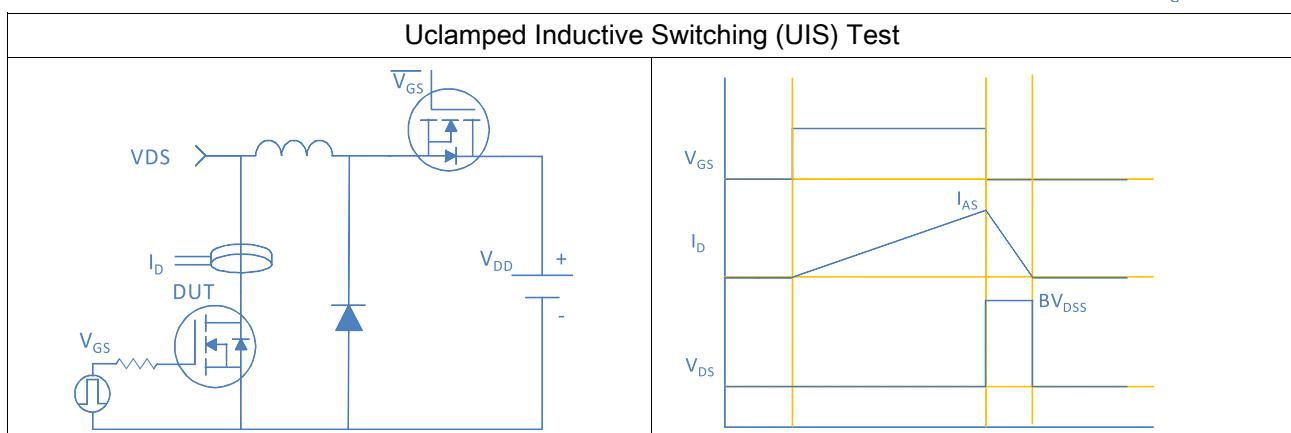
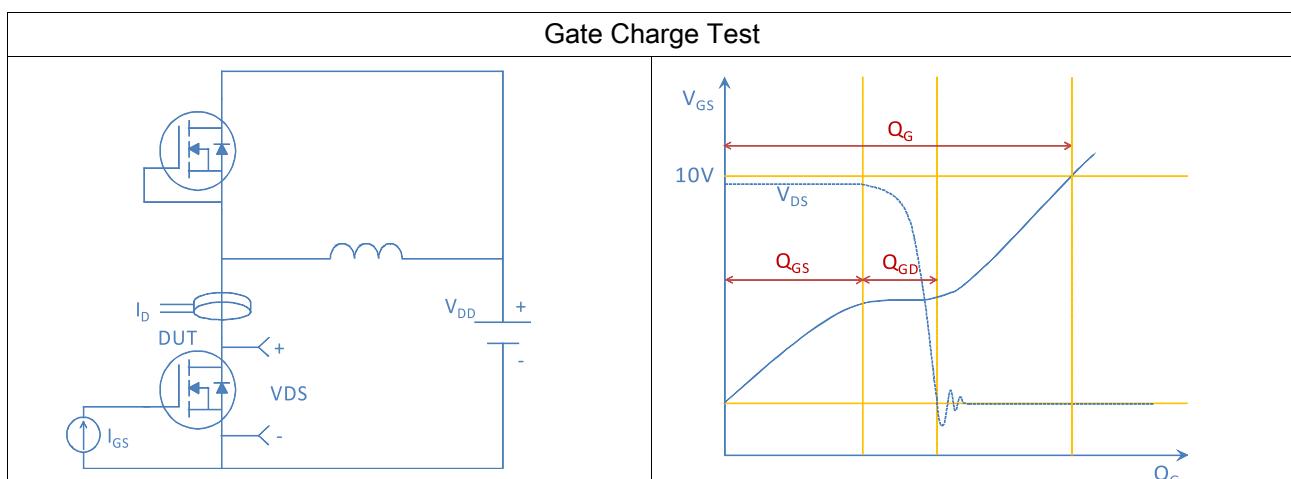
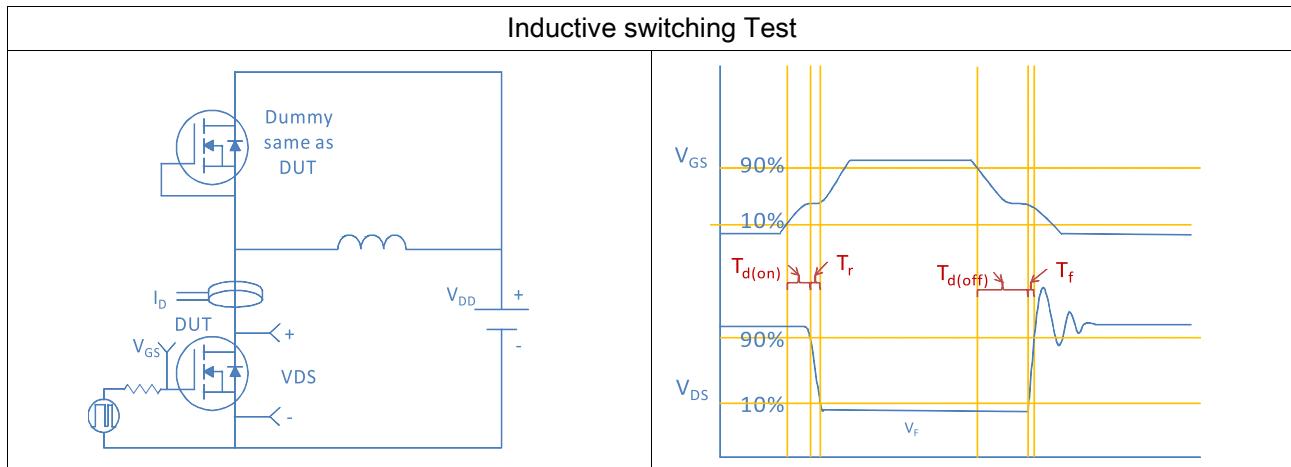
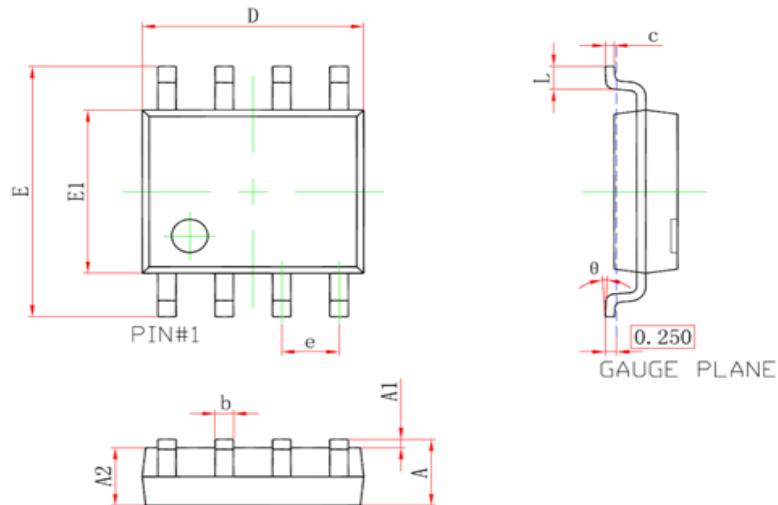
Fig 1. Typical Output Characteristics

Figure 2. On-Resistance vs. Gate-Source Voltage

Figure 3. On-Resistance vs. Drain Current and Gate Voltage

Figure 4. Normalized On-Resistance vs. Junction Temperature

Figure 5. Typical Transfer Characteristics

Figure 6. Typical Source-Drain Diode Forward Voltage


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient




Package Outline
SOIC-8, 8 leads


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.250	1.650	0.049	0.065
b	0.310	0.510	0.012	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (SBC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.031
θ	0°	8°	0°	8°